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NEWS RELEASE FOR IMMEDIATE RELEASE

S.E.C. INTRODUCES A NEW MOTORIZED TAKE-UP SYSTEM OPTION FOR THEIR WAFER MOUNTERS

MOORPARK, California, U.S.A., July 28, 2006 – Semiconductor Equipment Corporation of Moorpark, California has introduced a motorized take-up system to gather the liner from dicing tape onto a disposable core. The take-up system is compatible with all S.E.C. wafer/frame mounters (Models 3100/3150/300) and back lap tape applicators (Models 3100/3250). Many semiconductor dicing tapes have a protective liner, which has to be gathered and disposed of. This option makes that process effortless and convenient.

The motor also makes pulling the tape from the roll much easier since it is always pulling on the liner. It is an option on new machines and also is easily retrofitted on existing or older systems. For retrofit, the customer will have to drill/tap two holes on the side of the mounter and plug in the power cord to 110 AC.

This feature has been requested often and S.E.C. is happy to make it available now for less than \$2,000.00.

